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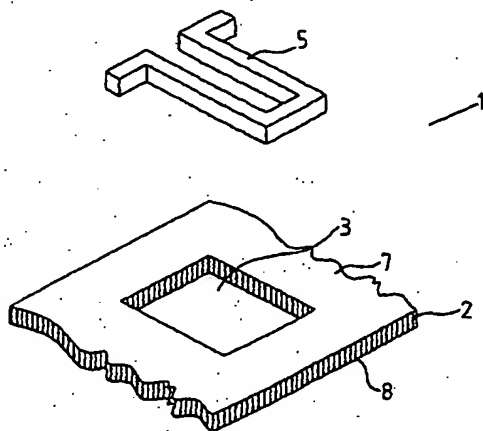
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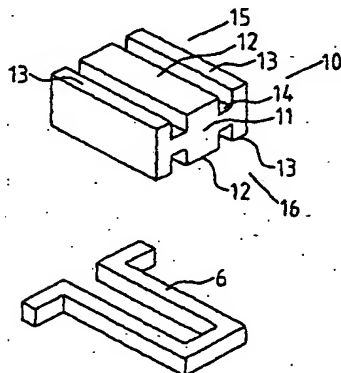
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(54) Title: **"A MAGNETIC STRUCTURE ASSEMBLY"**



(57) Abstract: There is illustrated the assembly of a dual inductor (1) on to a printed circuit board (2). A printed circuit board (2) has a through hole (3). Then the first winding (5), formed from a stamping, is mounted across the hole (3). Then, the first winding (5) is connected to the first face (7) of the PCB (2). Then, a core assembly (10) is inserted into the, hole (3) from the direction of a second face (8) of the PCB (2). Then, at some stage, for example as shown, the second winding (6) is inserted into the core assembly (10) and affixed to the bottom face (8) of the PCB (2).



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